Devcon 5 Minute® Epoxy Gel

Epoxy; Epoxide

Devcon

Message:

Thixotropic/non-migrating gel adhesive with excellent gap-filling properties.
Intended Use:
Bonding metal, ceramic, wood and vertical surface where gap-filling is needed.
Product features:
Good solvent resistance
Fills gaps to .250 inches
Non-sagging adhesive

General Information			
Features	thixotropic Solvent resistance Mobility Low to None		
Uses	Bonding Adhesive		
Appearance	Opacity		
Forms	Gel		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Volume	0.856	cm^3/g	
Solid content-by Volume	100	%	
Impact Resistance	13.7	kJ/m^2	
Service Temperature	-40 - 93	°C	
Work Time	4.0 - 7.0	min	
Tensile Shear Adhesion	17.2	MPa	ASTM D1002
Density [1]	1.17	g/cm^3	
Hardness	**Nominal Value**	**Unit**	**Test Method**
Durometer Hardness (Shore D)	80		ASTM D2240
Mechanical	**Nominal Value**	**Unit**	
Tensile Elongation (Break)	5.0	%	
Electrical	**Nominal Value**	**Unit**	**Test Method**
Dielectric Strength	17	kV/mm	ASTM D149
Thermoset	**Nominal Value**	**Unit**	**Test Method**
Thermoset Components			
	Mixing ratio by weight: 1.0		
Component a	Mixing ratio by capacity: 1.0		

	Mixing ratio by weight: 1.0		
Component B	Mixing ratio by capacity: 1.0		

Additional Information	Nominal Value	Unit	Test Method
Cured 7 days @ 75°F			

Uncured Properties	Nominal Value	Unit	Test Method
Curing Time	48	hr	

NOTE	
1.	Mixed

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